



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

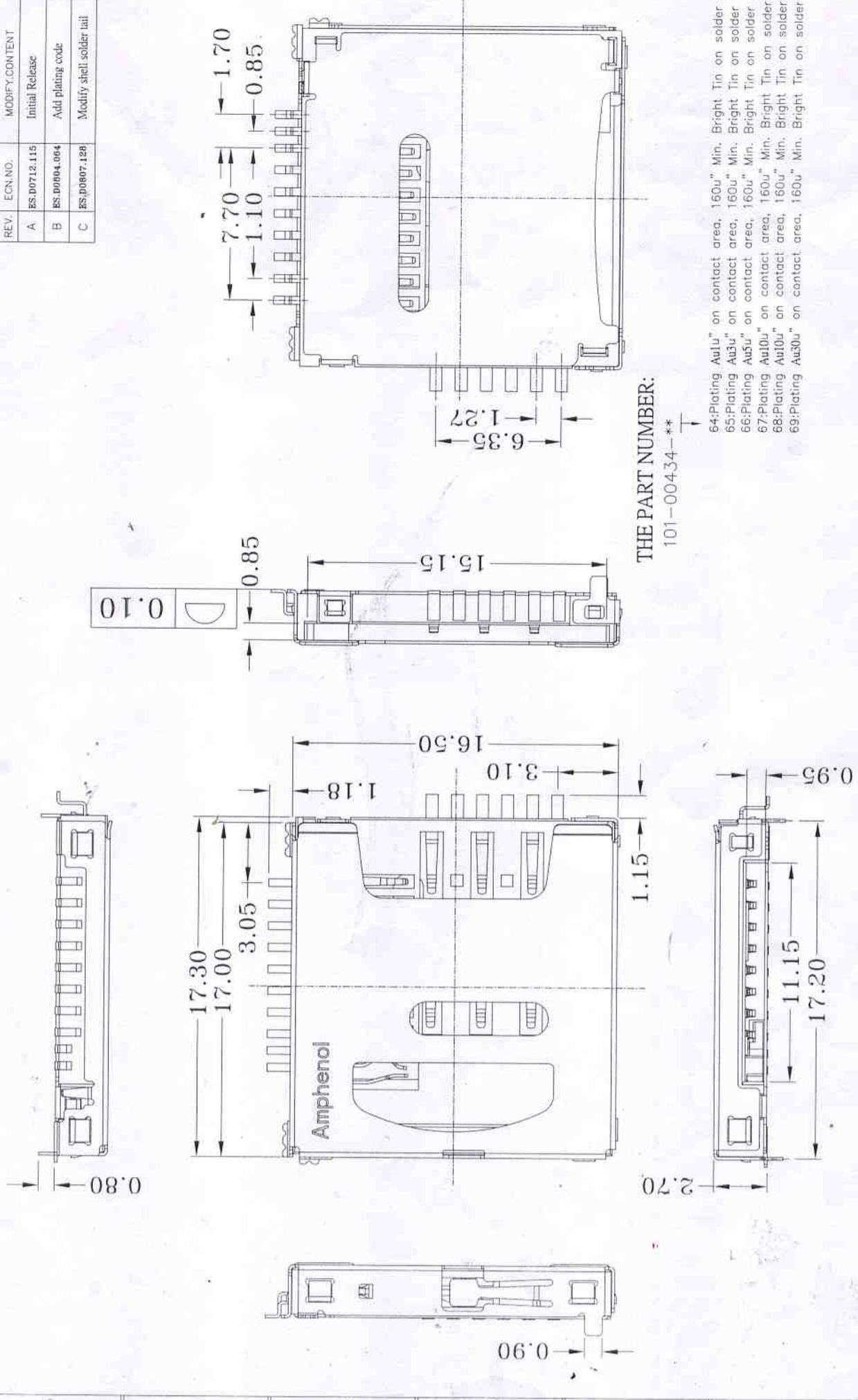
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REV.	ECN NO.	MODIFY CONTENT	DATE
A	BS.D00712.115	Initial Release	2007/12/25
B	BS.D0004.064	Add plating code	2008/1/14
C	BS.D00807.129	Modify shell solder tail	2008/07/24

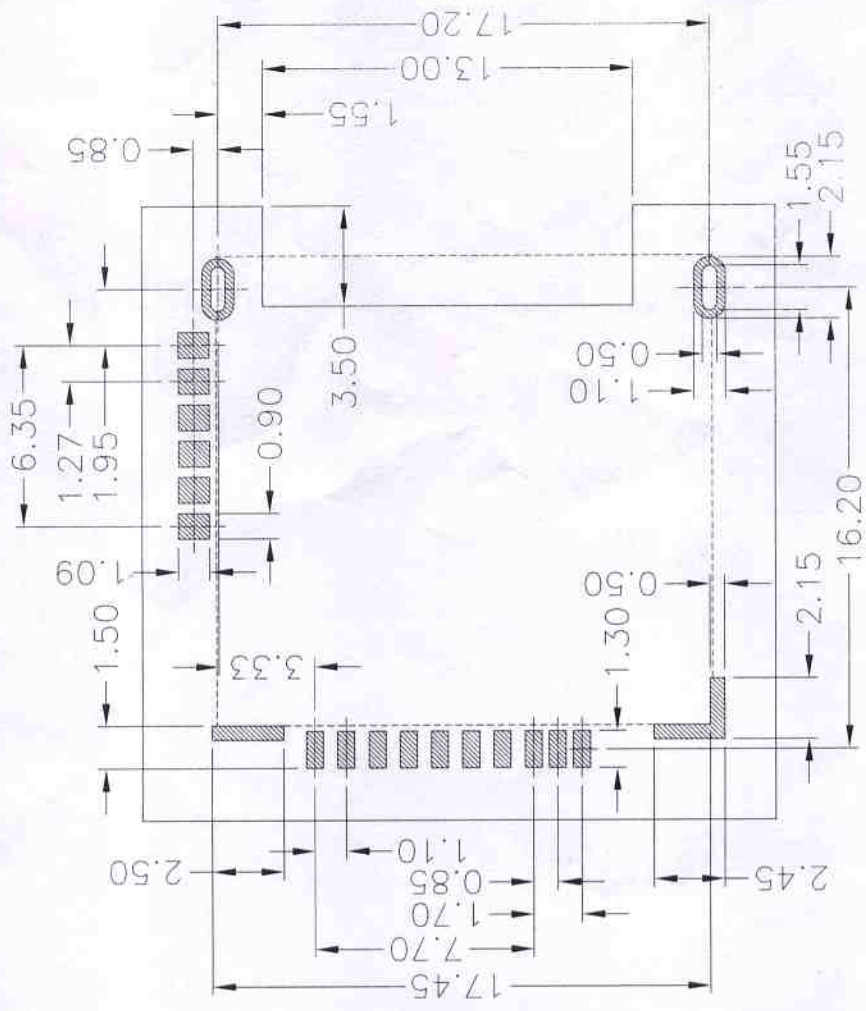
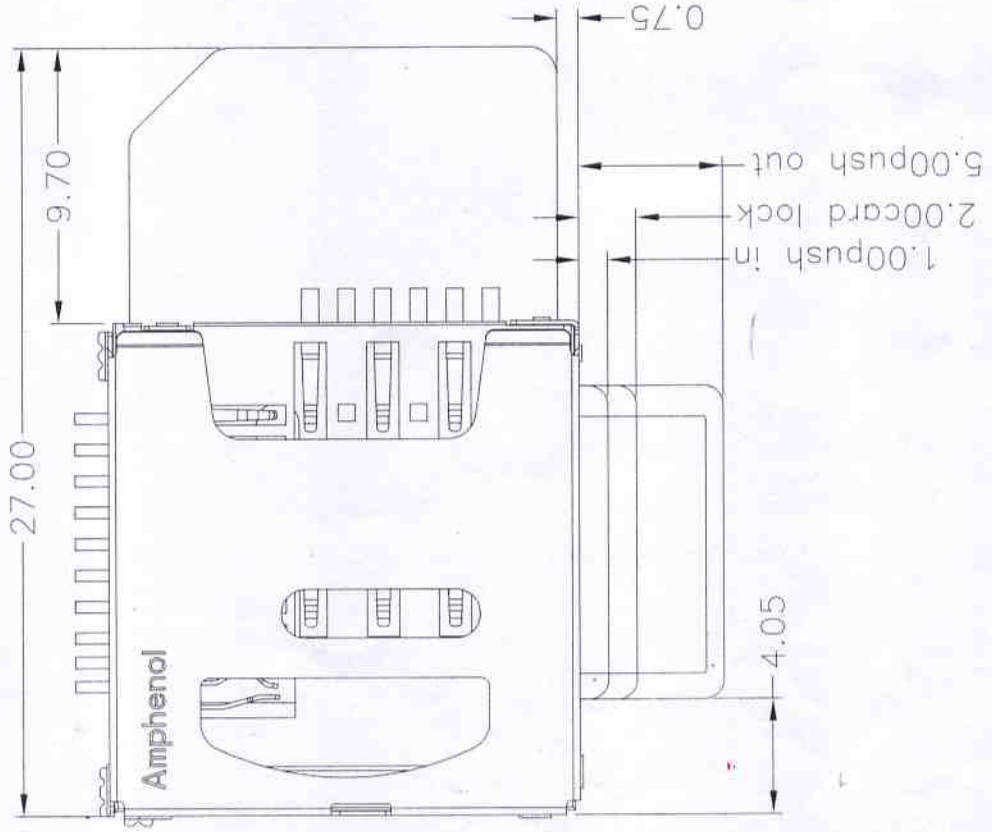


THE PART NUMBER:
101-00434-**-**

- 64:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
- 65:Plating Au30u" on contact area, 160u" Min. Bright Tin on solder tail.
- 66:Plating Au50u" on contact area, 160u" Min. Bright Tin on solder tail.
- 67:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
- 68:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
- 69:Plating Au30u" on contact area, 160u" Min. Bright Tin on solder tail.

GENERAL TOLERANCE		FILE NO.	PART NO.		DRAWN		MATERIAL		SCALE	
X:±0.50	x: ± 5*	10100434	10100434**		Paul		DATE		1:1	
.X±0.38	.x ± 2*	C	SIM+Micro-SD P/P CARD CONN.		CHECKED		2008/07/24		UNITS	
.XX±0.25	.xx ± 1*		1 OF 3		APPROVED		MM		MM	
Amphenol Shouhmin Industry										

REV.	ECN NO.	MODIFY CONTENT	DATE
A	ES:00712.115	Initial Release	2007/12/25
B	ES:00804.64	Add plating code	2008/1/14
C	ES:00807.128	Modify shell solder tail	2008/07/24



GENERAL	TOLERANCE	FILE NO.	PART NO.	10100434**	DRAWN	MATERIAL	SCALE
X, ±0.50	X, ± 5°	10100434	10100434**	SIM+Micro-SD P/P CARD CONN.	Paul	DATE	1:1
X ±0.58	X ± 2°	C	TITLE	2 OF 3	CHECKED	2008/07/24	UNITS
XX ± 0.25	.XX ± 1°		SHEET		APPROVED		MM
Amphenol Shouhmin Industry							

